

Amendments to the Specification:

Please replace paragraph [0007] with the following amended paragraph:

[0007] There are also known processes for the production of objects comprising plastic material substrates with layers located on them. Such a process is described in DE 195 23 444 A1. There a plastic is provided with a protective layer--by means of a plasma-supported CVD process (PICVDPACVDprocess)--by an electric high-frequency discharge at a reduced gas pressure. There it is a matter of achieving as high as possible a viscosity of this layer for the avoidance of embrittlement.

Please replace paragraph [0009] with the following amended paragraph:

[0009] Further processes for applying thin layers to plastic substrates are described in DE 34 13 019 A1, EP 0 422 323 A1, DE 04 116 A1 and others. There it is also a matter, inter alia, of the adhesion of the layer that is applied to the substrate and, namely, by means of the CVD or PICVD-sputter process. DE 100 10 766 shows and describes a process and a device for coating in particular curved substrates, for example, of eyeglasses.

Please replace paragraph [0013] with the following amended paragraph:

[0013] The inventors have perceived that a lasting and dependable fixing of the alternating layers to the plastic as well as of the alternating layers among one another is attainable if the alternating layers are applied to the plastic substrate with a quite definitive process, namely by means of the so-called PICV€ PICVD process (chemical plasma impulse vaporization).

Please replace paragraph [0014] with the following amended paragraph:

[0014] In the hitherto used PICV€ processes for applying layers to a substrate the interface of the substrate is disturbed or destroyed in its structure by the associated energy burden. This results in a reduction of the adhesiveness between substrate and adjoining layer. The inventors have perceived, accordingly, that the energy load which is associated with the plasma discharge must be minimized in order to enhance the adhesion. There it is a matters both of the quantity of the applied energy as well as also of the manner of its application. The admissible limit value of the load for achieving an adhesion sufficient in practice can be determined by experiment.

Please replace paragraph [0016] with the following amended paragraph:

[0016] As plastic material there come into consideration high-performance plastics which are

stable if possible up to a temperature of 100 degrees Celsius or above. Here again the ~~PICVC~~ PICVD process works out favorably, since the substrate temperature is kept relatively low. The layers generated are themselves hard and lasting.

Please replace paragraph [0025] with the following amended paragraph:

[0025] According to the invention it has proved that the alternating layers are fixable dependably and durably to the plastic material, and, namely, if they are applied with quite definite processes to the plastic substrate, namely, by means of the plasma-impulse process or by means of chemical vaporization or by means of ~~phase-impulse~~ plasma-impulse chemical vaporization.

Respectfully submitted,

John R. Hoffman
Registration No. 26,280

Attorney for Applicant

JFH/pmp

BAKER & DANIELS
111 East Wayne Street, Suite 800
Fort Wayne, IN 46802
Telephone: 260-424-8000
Facsimile: 260-460-1700

Enc. Return Postcard

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JOHN F. HOFFMAN, REG. NO. 26,280
Name of Registered Representative

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March 30, 2004
Date